

NCR169D

General Purpose Sensitive Gate Silicon Controlled Rectifier Reverse Blocking Thyristor

PNPN device designed for line-powered general purpose applications such as relay and lamp drivers, small motor controls, gate drivers for larger thyristors, and sensing and detection circuits. Supplied in a cost effective plastic TO-226AA package.

Features

- Sensitive Gate Allows Direct Triggering by Microcontrollers and Other Logic Circuits
- On-State Current Rating of 0.8 Amperes RMS at 80°C
- Surge Current Capability – 10 Amperes
- Immunity to dV/dt – 20 V/μsec Minimum at 110°C
- Glass-Passivated Surface for Reliability and Uniformity
- This is a Pb-Free Device

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1.) (T _J = -40 to 110°C, Sine Wave, 50 to 60 Hz; Gate Open)	V _{DRM} , V _{RRM}	400	Volts
On-State RMS Current (T _C = 80°C) 180° Conduction Angles	I _{T(RMS)}	0.8	Amp
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave, 60 Hz, T _J = 25°C)	I _{TSM}	10	Amps
Circuit Fusing Consideration (t = 10 ms)	I ² t	0.415	A ² s
Forward Peak Gate Power (T _A = 25°C, Pulse Width ≤ 1.0 μs)	P _{GM}	0.1	Watt
Forward Average Gate Power (T _A = 25°C, t = 20 ms)	P _{G(AV)}	0.10	Watt
Forward Peak Gate Current (T _A = 25°C, Pulse Width ≤ 1.0 μs)	I _{GM}	1.0	Amp
Reverse Peak Gate Voltage (T _A = 25°C, Pulse Width ≤ 1.0 μs)	V _{G(RM)}	5.0	Volts
Operating Junction Temperature Range @ Rate V _{RRM} and V _{DRM}	T _J	-40 to 110	°C
Storage Temperature Range	T _{stg}	-40 to 150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



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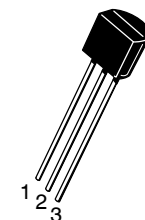
SCR
0.8 AMPERES RMS
400 VOLTS



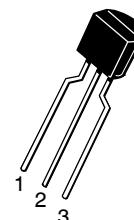
MARKING DIAGRAM

TO-92
(TO-226)
CASE 029-11
STYLE 10

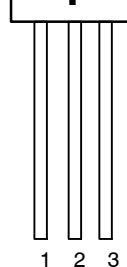
NCR
169D
ALYWW▪



STRAIGHT LEAD
BULK PACK



BENT LEAD
TAPE & REEL
AMMO PACK



A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
▪ = Pb-Free Package

(*Note: Microdot may be in either location)

PIN ASSIGNMENT

1	Cathode
2	Gate
3	Anode

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

NCR169D

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal Resistance – Junction to Case	$R_{\theta JC}$	75	$^{\circ}C/W$
– Junction to Ambient	$R_{\theta JA}$	200	$^{\circ}C/W$
Lead Solder Temperature (< 1/16" from case, 10 secs max)	T_L	260	$^{\circ}C$

Electrical Characteristics ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Peak Repetitive Forward or Reverse Blocking Current (Note 1.) ($V_D = \text{Rated } V_{DRM}$ and V_{RRM} ; $R_{GK} = 1.0 \text{ k}\Omega$)	I_{DRM}, I_{RRM}	$T_C = 25^{\circ}C$ $T_C = 110^{\circ}C$	– –	– –	10 0.1	μA mA
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ON CHARACTERISTICS

Peak Forward On-State Voltage* ($I_{TM} = 1.0 \text{ Amp Peak @ } T_A = 25^{\circ}C$)	V_{TM}		–	–	1.7	Volts
Gate Trigger Current (Continuous dc) (Note 2.) ($V_{AK} = 12 \text{ V}, R_L = 100 \text{ Ohms}$)	I_{GT}	$T_C = 25^{\circ}C$	–	40	200	μA
Holding Current (Note 2.) ($V_{AK} = 12 \text{ V}, I_{GT} = 0.5 \text{ mA}$)	I_H	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	– –	0.5 –	5.0 10	mA
Latch Current ($V_{AK} = 12 \text{ V}, I_{GT} = 0.5 \text{ mA}, R_{GK} = 1.0 \text{ k}$)	I_L	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	– –	0.6 –	10 15	mA
Gate Trigger Voltage (Continuous dc) (Note 2.) ($V_{AK} = 12 \text{ V}, R_L = 100 \text{ Ohms}, I_{GT} = 10 \text{ mA}$)	V_{GT}	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	– –	0.62 –	0.8 1.2	Volts

DYNAMIC CHARACTERISTICS

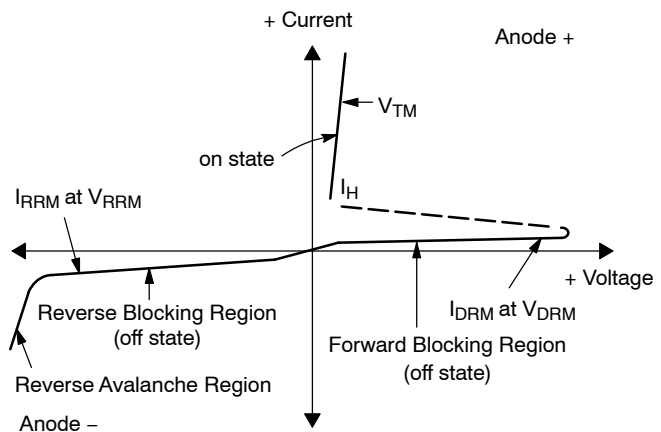
Critical Rate of Rise of Off-State Voltage ($V_D = \text{Rated } V_{DRM}$, Exponential Waveform, $R_{GK} = 1000 \text{ Ohms}$, $T_J = 110^{\circ}C$)	dV/dt	20	35	–	$V/\mu s$
Critical Rate of Rise of On-State Current ($I_{PK} = 20 \text{ A}; P_w = 10 \mu sec; di/dt = 1.0 \text{ A}/\mu sec, I_{gt} = 20 \text{ mA}$)	di/dt	–	–	50	$A/\mu s$

*Indicates Pulse Test: Pulse Width $\leq 1.0 \text{ ms}$, Duty Cycle $\leq 1\%$.

- $R_{GK} = 1000 \text{ Ohms}$ included in measurement.
- Does not include R_{GK} in measurement.

Voltage Current Characteristic of SCR

Symbol	Parameter
V_{DRM}	Peak Repetitive Off State Forward Voltage
I_{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Off State Reverse Voltage
I_{RRM}	Peak Reverse Blocking Current
V_{TM}	Peak on State Voltage
I_H	Holding Current



NCR169D

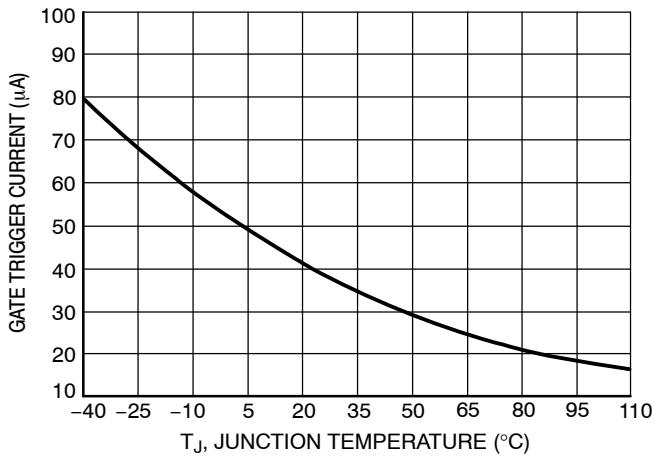


Figure 1. Typical Gate Trigger Current versus Junction Temperature

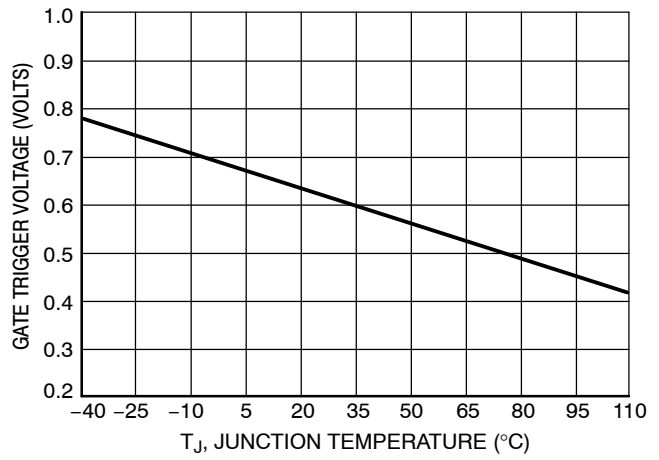


Figure 2. Typical Gate Trigger Voltage versus Junction Temperature

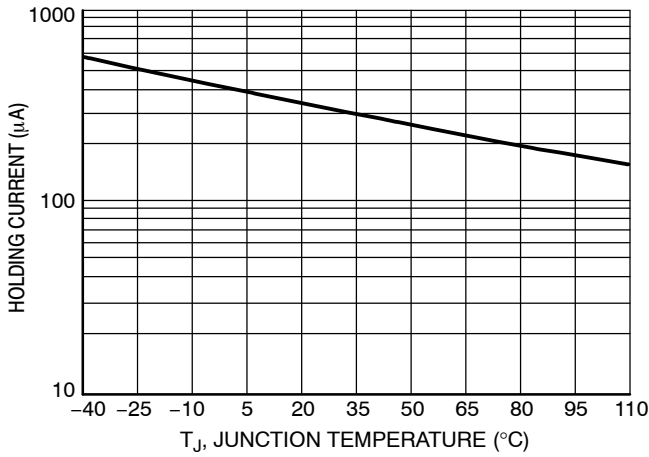


Figure 3. Typical Holding Current versus Junction Temperature

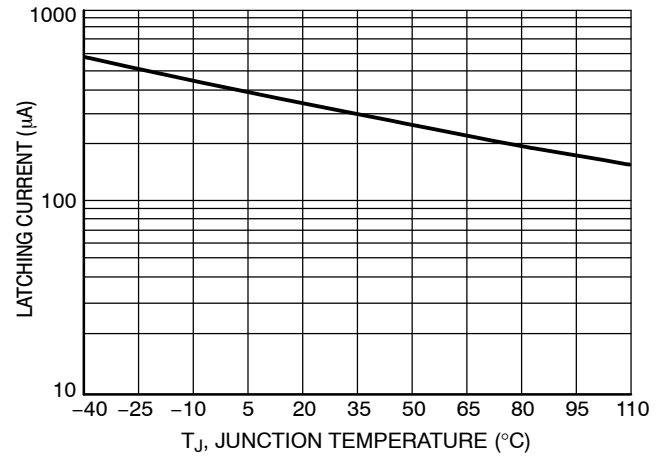


Figure 4. Typical Latching Current versus Junction Temperature

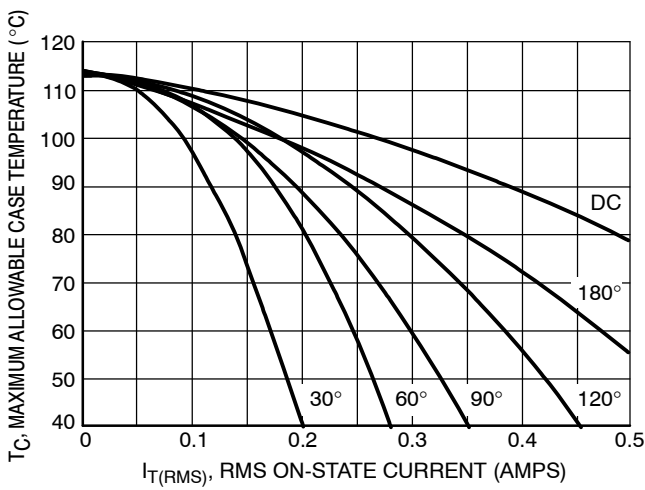


Figure 5. Typical RMS Current Derating

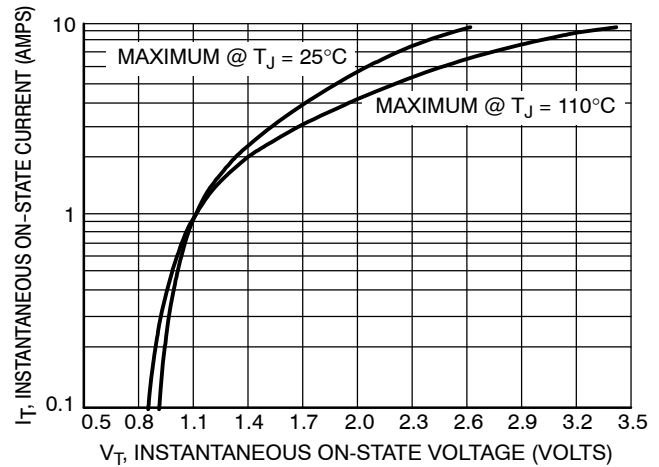


Figure 6. Typical On-State Characteristics

NCR169D

TO-92 EIA RADIAL TAPE IN FAN FOLD BOX OR ON REEL

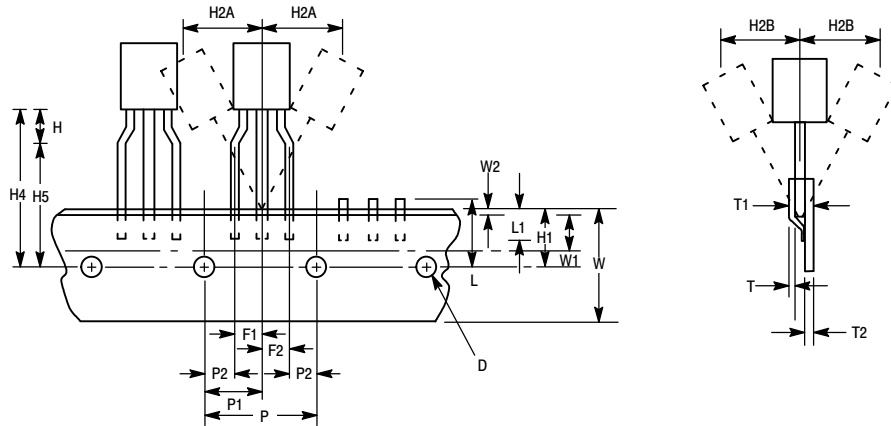


Figure 7. Device Positioning on Tape

Symbol	Item	Specification			
		Inches		Millimeter	
		Min	Max	Min	Max
D	Tape Feedhole Diameter	0.1496	0.1653	3.8	4.2
D2	Component Lead Thickness Dimension	0.015	0.020	0.38	0.51
F1, F2	Component Lead Pitch	0.0945	0.110	2.4	2.8
H	Bottom of Component to Seating Plane	.059	.156	1.5	4.0
H1	Feedhole Location	0.3346	0.3741	8.5	9.5
H2A	Deflection Left or Right	0	0.039	0	1.0
H2B	Deflection Front or Rear	0	0.051	0	1.0
H4	Feedhole to Bottom of Component	0.7086	0.768	18	19.5
H5	Feedhole to Seating Plane	0.610	0.649	15.5	16.5
L	Defective Unit Clipped Dimension	0.3346	0.433	8.5	11
L1	Lead Wire Enclosure	0.09842	-	2.5	-
P	Feedhole Pitch	0.4921	0.5079	12.5	12.9
P1	Feedhole Center to Center Lead	0.2342	0.2658	5.95	6.75
P2	First Lead Spacing Dimension	0.1397	0.1556	3.55	3.95
T	Adhesive Tape Thickness	0.06	0.08	0.15	0.20
T1	Overall Taped Package Thickness	-	0.0567	-	1.44
T2	Carrier Strip Thickness	0.014	0.027	0.35	0.65
W	Carrier Strip Width	0.6889	0.7481	17.5	19
W1	Adhesive Tape Width	0.2165	0.2841	5.5	6.3
W2	Adhesive Tape Position	.0059	0.01968	.15	0.5

NOTES:

1. Maximum alignment deviation between leads not to be greater than 0.2 mm.
2. Defective components shall be clipped from the carrier tape such that the remaining protrusion (L) does not exceed a maximum of 11 mm.
3. Component lead to tape adhesion must meet the pull test requirements.
4. Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.
5. Holddown tape not to extend beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.
6. No more than 1 consecutive missing component is permitted.
7. A tape trailer and leader, having at least three feed holes is required before the first and after the last component.
8. Splices will not interfere with the sprocket feed holes.

NCR169D

ORDERING & SHIPPING INFORMATION: MCR100 Series packaging options, Device Suffix

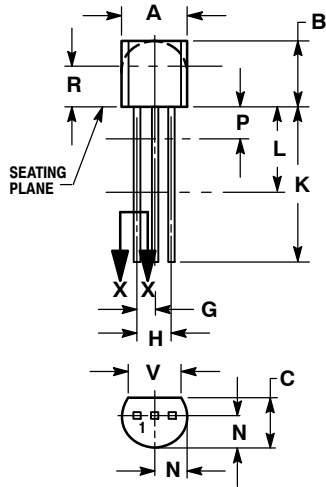
Device	Description of TO92 Tape Orientation	Shipping
NCR169DG	N/A, Bulk	Bulk in Box (5K/Box) (Pb-Free)
NCR169DRLRAG	Round side of TO92 and adhesive tape visible	Radial Tape and Reel (2K/Reel) (Pb-Free)

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

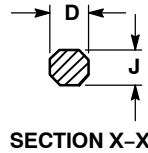
NCR169D

PACKAGE DIMENSIONS

TO-92 (TO-226)
CASE 029-11
ISSUE AM



STRAIGHT LEAD
BULK PACK



SECTION X-X

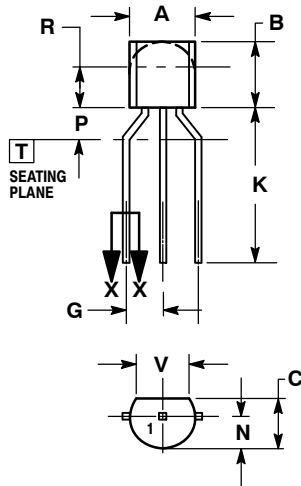
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

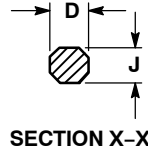
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---

STYLE 10:

- PIN 1. CATHODE
- GATE
- ANODE



BENT LEAD
TAPE & REEL
AMMO PACK



SECTION X-X

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
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3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS	
	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

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